

MOS FIELD EFFECT TRANSISTOR 2SK3713

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3713 is N-channel MOS Field Effect Transistor designed for high voltage and high speed switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3713-SK	TO-262

FEATURES

- Super high V_{GS(off)}: V_{GS(off)} = 3.8 to 5.8 V
- Low Crss: Crss = 6.5 pF TYP.
- Low Qg: Qg = 25 nC TYP.
- Low on-state resistance:

 $R_{DS(on)} = 0.83 \Omega MAX. (V_{GS} = 10 V, I_D = 5 A)$

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

VDSS	600	V
Vgss	±30	V
ID(DC)	±10	Α
ID(pulse)	±35	Α
P _{T1}	100	W
P _{T2}	1.5	W
Tch	150	°C
Tstg	-55 to +150	°C
las	10	Α
Eas	6	mJ
	VGSS ID(DC) ID(pulse) PT1 PT2 Tch Tstg IAS	VGSS ±30 ID(DC) ±10 ID(pulse) ±35 PT1 100 PT2 1.5 Tch 150 Tstg -55 to +150 IAS 10

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25°C, V_{DD} = 100 V, L = 100 μ H, R_G = 25 Ω , V_{GS} = 20 \rightarrow 0 V

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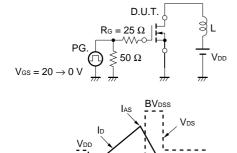
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ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 600 V, V _{GS} = 0 V			100	μΑ
Gate Leakage Current	Igss	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	3.8	4.8	5.8	>
Forward Transfer Admittance Note	y fs	V _{DS} = 10 V, I _D = 5 A	2.5	4.6		S
Drain to Source On-state Resistance Note	RDS(on)	V _G S = 10 V, I _D = 5 A		0.68	0.83	Ω
Input Capacitance	Ciss	V _{DS} = 10 V		1460		pF
Output Capacitance	Coss	V _{GS} = 0 V		250		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		6.5		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 150 V, I _D = 5 A		26		ns
Rise Time	t r	V _{GS} = 10 V		8.5		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		30		ns
Fall Time	t f			5.2		ns
Total Gate Charge	Q _G	V _{DD} = 450 V		25		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		12		nC
Gate to Drain Charge	Q _{GD}	I _D = 10 A		9		nC
Body Diode Forward Voltage Note	V _F (S-D)	I _F = 10 A, V _{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	trr	I _F = 10 A, V _{GS} = 0 V		450		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		4.0		μC

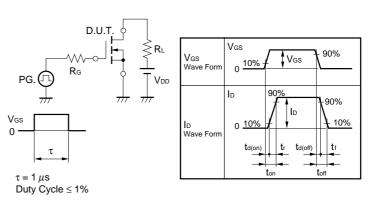
Note Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

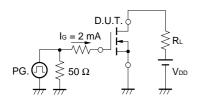


Starting Tch

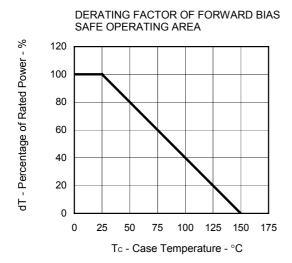
TEST CIRCUIT 2 SWITCHING TIME

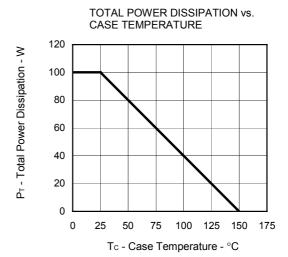


TEST CIRCUIT 3 GATE CHARGE

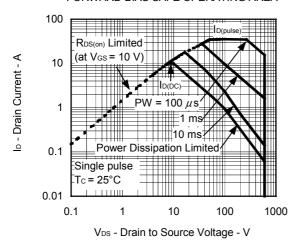


TYPICAL CHARACTERISTICS (TA = 25°C)

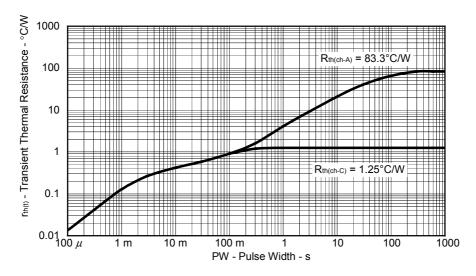




FORWARD BIAS SAFE OPERATING AREA

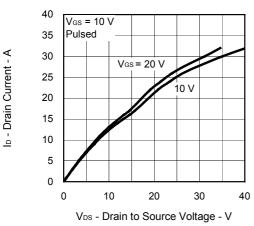


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

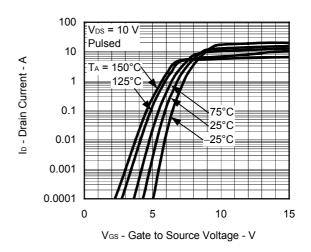


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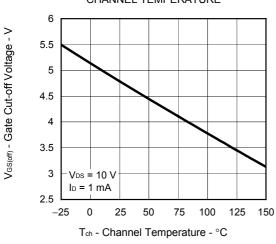




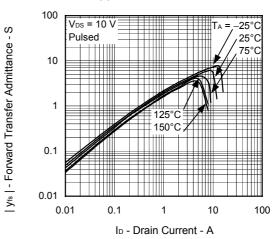
FORWARD TRANSFER CHARACTERISTICS



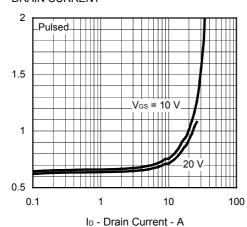
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



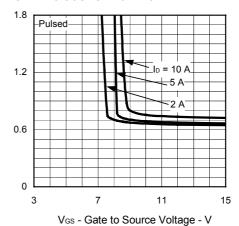
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



 $\mathsf{R}_{\mathsf{DS}(m)}$ - Drain to Source On-state Resistance - Ω

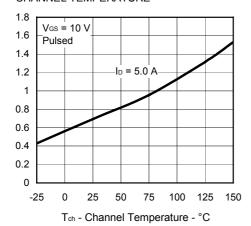
 $\mathsf{R}_{\mathsf{DS}(\varpi)}$ - Drain to Source On-state Resistance - Ω

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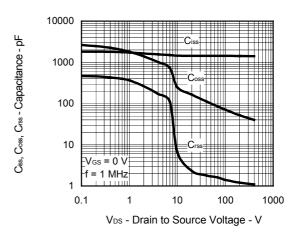
IF - Diode Forward Current - A

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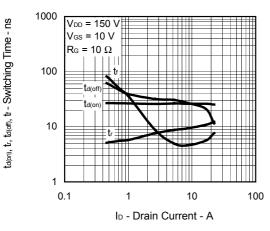
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



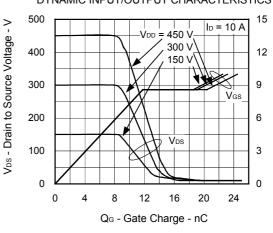
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



SWITCHING CHARACTERISTICS

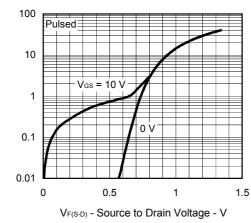


DYNAMIC INPUT/OUTPUT CHARACTERISTICS

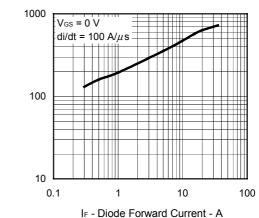


Ves - Gate to Source Voltage - V

SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

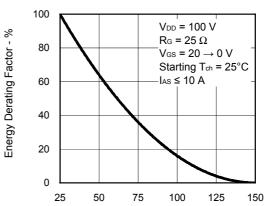


fr - Reverse Recovery Time - ns

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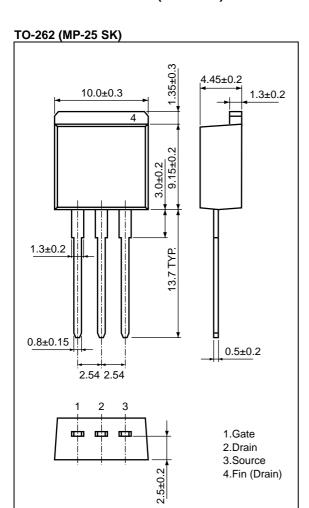
L - Inductive Load - mH

SINGLE AVALANCHE ENERGY DERATING FACTOR

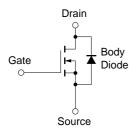


Starting Tch - Starting Channel Temperature - °C

wPACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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